



# DATA SHEET

## 2N7002

### N-CHANNEL ENHANCEMENT MODE FIELD EFFECT TRANSISTOR

**VOLTAGE** 60 Volts

**CURRENT** 200 mAmp

### FEATURE

N-channel enhancement mode field effect transistor, designed for high speed pulse amplifier and drive application, which is manufactured by the N-channel DMOS process.

Both normal and Pb free product are available :

Normal : 80~95% Sn, 5~20% Pb

Pb free: 98.5% Sn above

### MECHANICS DATA

High density cell design for low  $R_{DS(ON)}$

Voltage controlled small signal switching.

Rugged and reliable.

High saturation current capability.

High-speed switching. CMOS logic compatible.

CMOS logic compatible input.

Not thermal runaway.

No secondary breakdown.

Marking Code: S72

### ABSOLUTE MAXIMUM RATING

$T_A=25^{\circ}C$  Unless otherwise noted

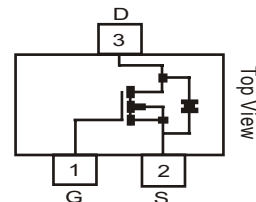
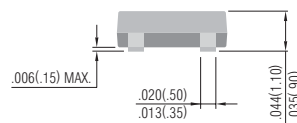
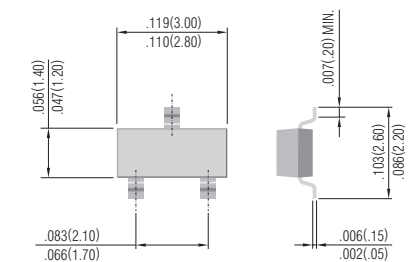
PARAMETER	SYMBOL	Value	UNIT
Drain-Source Voltage	$V_{DSS}$	60	V
Drain-gate Voltage	$V_{DRG}$	60	V
Gate-Source Voltage	$V_{GSS}$	20	V
Maximum Drain Current-Continue -Pulse (Note1)	$I_D$	200 800	mA
Maximum power Dissipation Derating Above 25°C	$P_D$	350	mW
Operating and Storage Temperature Range	$T_J, T_{STG}$	-55 to +150	°C
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	357	°C/W

Note:

1.Pulse Test: Pulse Width <300 us, Duty Cycle <2.0%.

SOT-23

Unit: inch ( mm )



Top View



## ELECTRICAL CHARACTERISTICS

TA=25°C Unless otherwise noted

PARAMETER	SYMBOL	CONDITION	MIN	TYP	MAX	UNIT
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V, I <sub>D</sub> =10 μA	60	105	—	V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C V <sub>DS</sub> =60V, V <sub>GS</sub> =0V, T <sub>J</sub> =125°C	—	—	1.0 0.5	μA mA
Gate-Body Leakage, Forward	I <sub>GSSF</sub>	V <sub>DS</sub> =0, V <sub>GS</sub> =20V	—	—	100	nA
Gate-Body Leakage, Reverse	I <sub>GSSR</sub>	V <sub>DS</sub> =0, V <sub>GS</sub> =-20V	—	—	-100	nA
<b>ON CHARACTERISTIC(note1)</b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250 μA	1	2.1	2.5	V
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =500mA, T <sub>J</sub> =25°C	—	3.7	7.5	Ω
Drain-Source On-Voltage	V <sub>DS(ON)</sub>	V <sub>GS</sub> =10V, I <sub>D</sub> =500mA V <sub>GS</sub> =5.0V, I <sub>D</sub> =50mA	—	—	3.75 1.5	V
On-State Drain Current	I <sub>D(ON)</sub>	V <sub>GS</sub> =10V, V <sub>DS</sub> ≥ 2V <sub>DS(ON)</sub>	500	—	—	mA
Forward Transconductance	G <sub>FS</sub>	V <sub>DS</sub> ≥ 2V <sub>DS(ON)</sub> , I <sub>D</sub> =200mA	80	—	—	mS
<b>DYNAMIC CHARACTERISTICS</b>						
Input Capacitance	C <sub>ISS</sub>	V <sub>DS</sub> =25V, V <sub>GS</sub> =0V, F=1.0MHz	—	—	50	pF
Output Capacitance	C <sub>OSS</sub>		—	—	25	pF
Reverse Transfer Capacitance	C <sub>RSS</sub>		—	—	5	pF
Turn-On Time	T <sub>ON</sub>	V <sub>DD</sub> =30V, R <sub>L</sub> =25 Ω, I <sub>D</sub> =500mA V <sub>GS</sub> =10V, R <sub>GEN</sub> =25 Ω	—	—	20	ns
Turn-Off Time	T <sub>OFF</sub>		—	—	20	ns

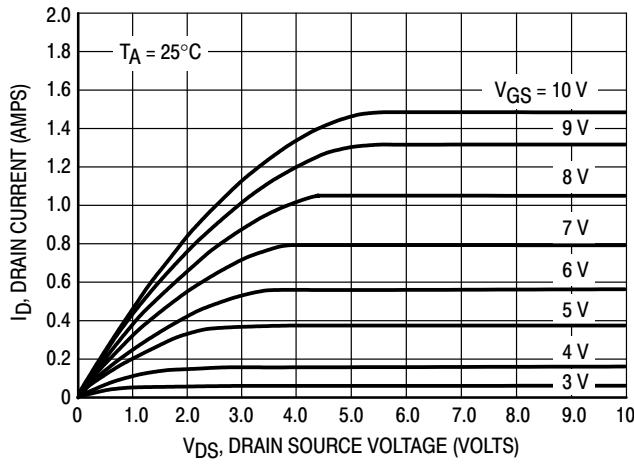


Figure 1. Ohmic Region

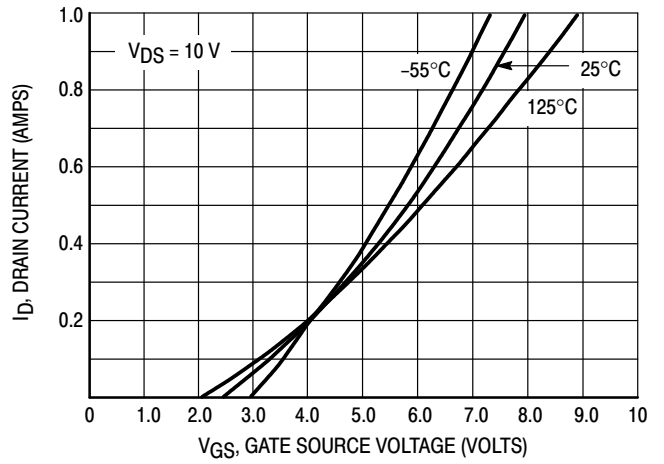


Figure 2. Transfer Characteristics

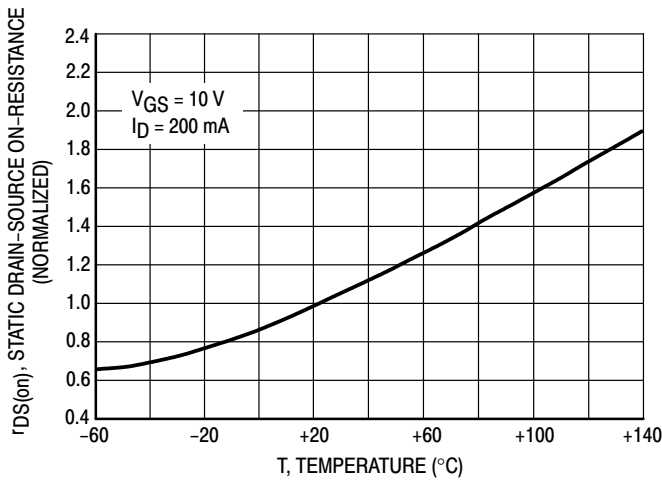


Figure 3. Temperature versus Static Drain-Source On-Resistance

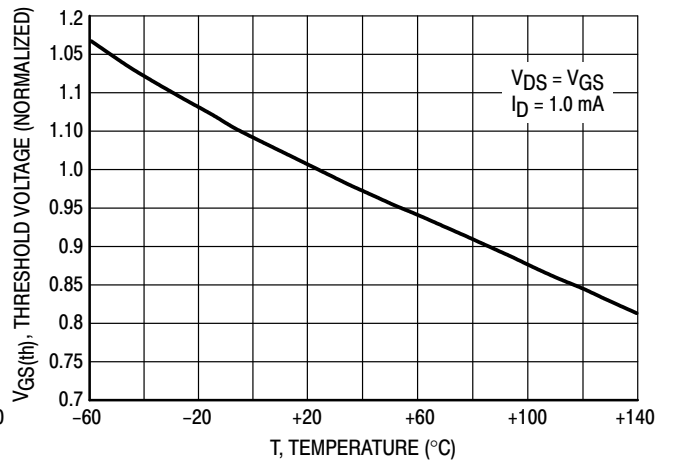


Figure 4. Temperature versus Gate Threshold Voltage